

ABSTRACT**METHOD OF PREPARING CHEMICAL FOR FORMING PROTECTIVE MEMBRANE**

[Summary]

5 [Problem] The problem addressed by the present invention is to provide: a method for preparing a chemical that is for forming a protective membrane and that, in a method for producing a wafer having a bumpy pattern at the surface, at least a portion of the bumpy pattern containing the element silicon, improves a cleaning step during which it is easy for pattern collapse to be
10 induced, in particular has superior persistence (pot life) of the improvement effect, and forms a water-repellent protective membrane at the surface of the bumpy pattern of the wafer; and the chemical. [Solution] The method for preparing a chemical, which forms a water-repellant protective membrane, has a non-aqueous organic solvent, a silylating agent, and an acid or base, and is
15 for forming a water-repellant protective membrane at the surface of at least the concave portions of the bumpy pattern when cleaning the wafer, is characterized by having: a dehydrating step for causing the water concentration in the non-aqueous organic solvent to be no greater than 200 ppm by mass; and a mixing step for mixing the non-aqueous organic solvent
20 after the dehydrating step, the silylating agent, and the acid or base.